2SC2632

Rev.E Mar.-2016

蓝箭电子 BLUE ROCKET ELECTRONICS

DATA SHEET

描述 / Descriptions

TO-92LM 塑封封装 NPN 半导体三极管。Silicon NPN transistor in a TO-92LM Plastic Package.

特征 / Features

较好的放大线性，集电-发射极击穿电压高，输出电容小。

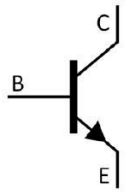
Satisfactory linearity of forward current transfer ratio h_{FE},High collector to emitter Voltage V_{CEO},Small collector output capacitance C_{ob}..

用途 / Applications

用于低频高压放大输出，与 2SA1124 互补。

For low-frequency high breakdown voltage amplification complementary to 2SA1124.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1：Base　　PIN 2：Collector　　PIN 3：Emitter

放大及印章代码 / h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	R	S
h_{FE} Range	130～220	185～330

极限参数 / Absolute Maximum Ratings(Ta=25℃)

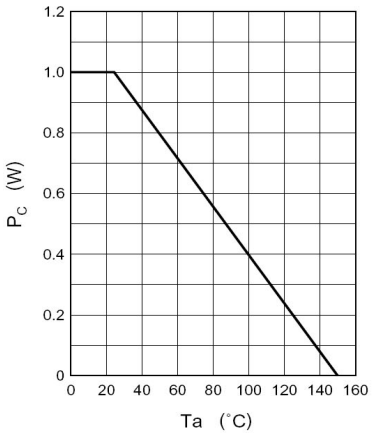
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	150	V
Collector to Emitter Voltage	V_{CEO}	150	V
Emitter to Base Voltage	V_{EBO}	5	V
Collector Current (DC)	I_C	50	mA
Collector Current (Pulse)	I_{CP}	100	mA
Collector Power Dissipation	P_C	1	W
Junction Temperature	T_j	150	℃
Storage Temperature Range	T_{stg}	-55～150	℃

电性能参数 / Electrical Characteristics(Ta=25℃)

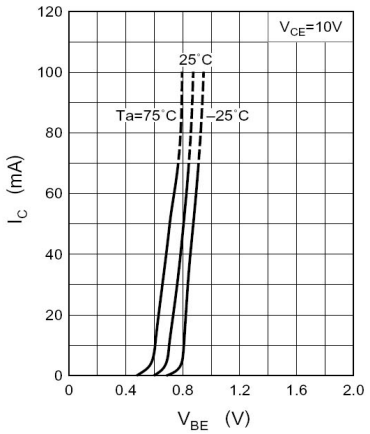
参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Emitter Breakdown Voltage	V_{CEO}	I_C=0.1mA I_B=0	150			V
Emitter to Base Breakdown Voltage	V_{EBO}	I_E=10μA I_C=0	5			V
Collector Cut-Off Current	I_{CBO}	V_{CB}=100V I_E=0			1	μA
DC Current Gain	h_{FE}	V_{CE}=5V I_C=10mA	130		330	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	I_C=30mA I_B=3mA			1	V
Transition Frequency	f_T	V_{CB}=10V I_E=-10mA f=200MHz		160		MHz
Collector Output Capacitance	C_{ob}	V_{CB}=10V I_E=0 f=1MHz			3	pF
Noise Voltage	NV	V_{CE}=10V I_C=1mA G_V=80dB Rg=100kΩ Function=FLAT		150	300	mV

电参数曲线图 / Electrical Characteristic Curve

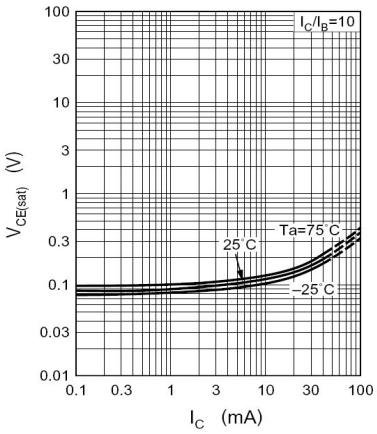
P_C — Ta



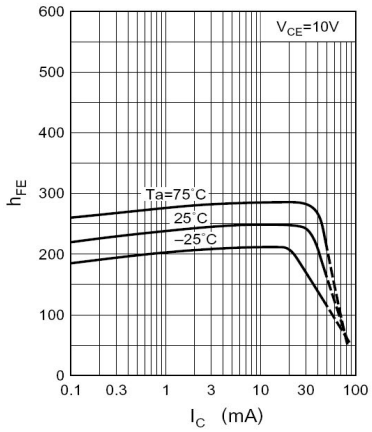
I_C — V_{BE}



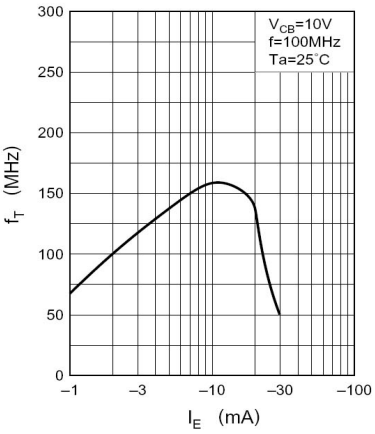
$V_{CE(sat)}$ — I_C



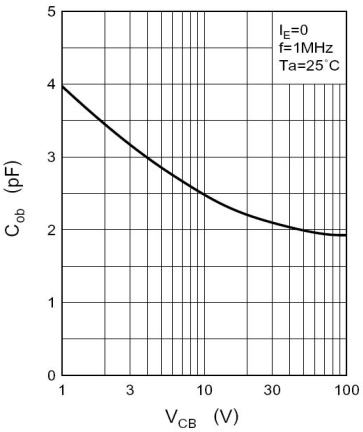
h_{FE} — I_C



f_T — I_E

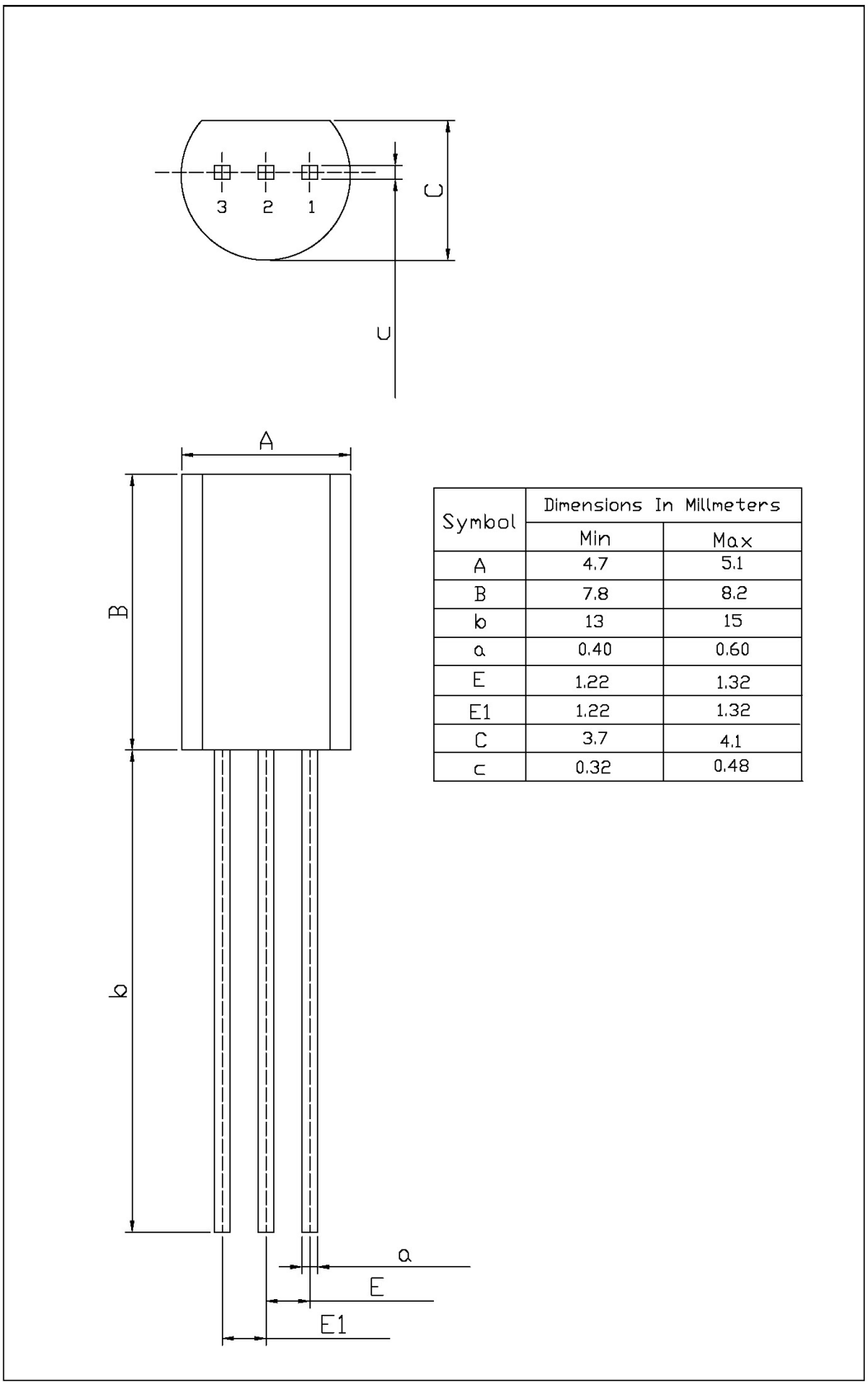


C_{ob} — V_{CB}



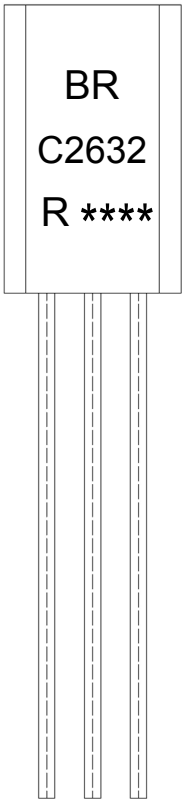
外形尺寸图 / Package Dimensions

TO-92LM Unit: mm



Symbol	Dimensions In Millmeters	
	Min	Max
A	4.7	5.1
B	7.8	8.2
b	13	15
a	0.40	0.60
E	1.22	1.32
E1	1.22	1.32
C	3.7	4.1
c	0.32	0.48

印章说明 / Marking Instructions



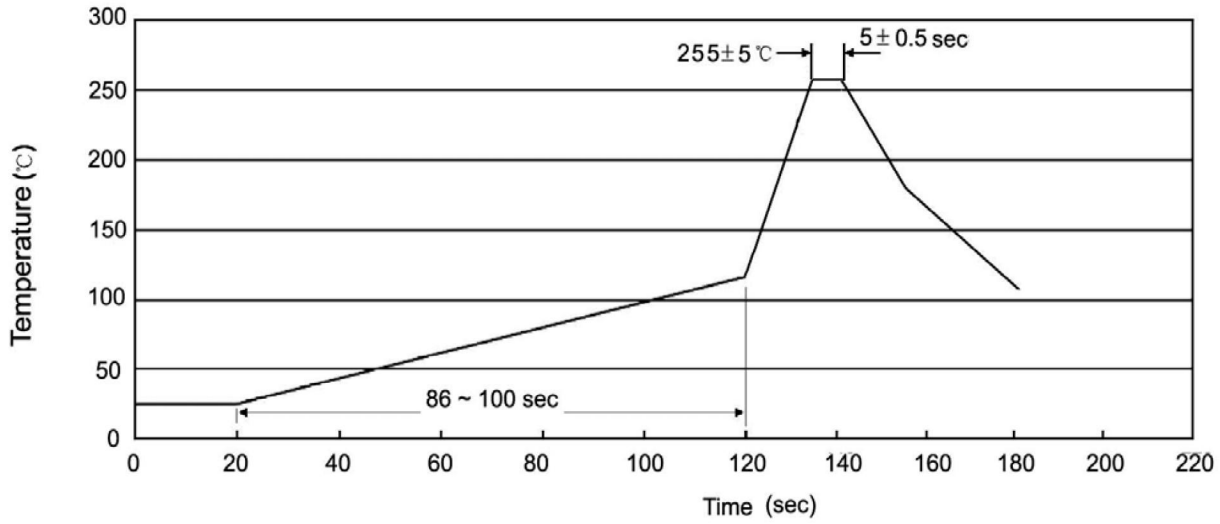
说明：

BR:	为公司代码
C2632：	为型号代码
R:	为 h_{FE} 分档代码
****：	为生产批号代码，随生产批号变化。

Note:

BR:	Company Code.
C2632:	Product Type.
R:	h_{FE} Classifications Symbol
****:	Lot No. Code,code change with Lot No.

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

1、预热温度 25～150℃，时间 60～90sec;

2、峰值温度 255±5℃，时间持续为 5±0.5sec;

3、焊接制程冷却速度为 2～10℃/sec.

Note:

1.Preheating:25~150℃, Time:60~90sec.

2.Peak Temp.:255±5℃, Duration:5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5℃　　时间：10±1 sec.　　Temp.:270±5℃　　Time:10±1 sec

包装规格 / Packaging SPEC.

散件包装 / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
TO-92LM	1,000	8	8,000	5	40,000	135×190	237×172×102	560×245×195

编带包装 / AMMO

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)	
	Units/tape 只/纸带	Tape/Inner Box 纸带/盒	Rows/Inner Box 纸带层/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Inner Box 盒	Outer Box 箱
TO-92LM	2,500	1	100	10	25,000	328×230×42	小箱 480×346×235 大箱 547×407×268

使用说明 / Notices